

# Surface Mount Ultrafast Power Rectifiers

## MURS260T3G, SURS8260T3G, SURS8260T3G-VF01

Ideally suited for high voltage, high frequency rectification, or as free wheeling and protection diodes in surface mount applications where compact size and weight are critical to the system.

### Features

- Small Compact Surface Mountable Package with J-Bend Leads
- Rectangular Package for Automated Handling
- High Temperature Glass Passivated Junction
- Low Forward Voltage Drop (1.20 Volts Max @ 2.0 A,  $T_J = 150^\circ\text{C}$ )
- AEC-Q101 Qualified and PPAP Capable
- SURS8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free and are RoHS Compliant

### Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 95 mg (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes:  $260^\circ\text{C}$  Max. for 10 Seconds
- Polarity: Polarity Band Indicates Cathode Lead
- ESD Ratings:
  - ◆ Human Body Model = 3B (> 8 kV)

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	600	V
Working Peak Reverse Voltage	$V_{RWM}$		
DC Blocking Voltage	$V_R$		
Average Rectified Forward Current	$I_{F(AV)}$	2.0 @ $T_L = 125^\circ\text{C}$	A
Non-Repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	$I_{FSM}$	35	A
Operating Junction Temperature	$T_J$	-65 to +175	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

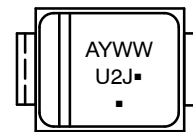
\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## ULTRAFAST RECTIFIERS 2 AMPERES 600 VOLTS



SMB  
CASE 403A

### MARKING DIAGRAM



- U2J = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MURS260T3G	SMB (Pb-Free)	2,500 / Tape & Reel
SURS8260T3G	SMB (Pb-Free)	2,500 / Tape & Reel
SURS8260T3G-VF01	SMB (Pb-Free)	2,500 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MURS260T3G, SURS8260T3G, SURS8260T3G-VF01

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead ( $T_L = 25^\circ\text{C}$ )	$R_{\theta JL}$	13	$^\circ\text{C/W}$

## ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 1) ( $i_F = 2.0\text{ A}$ , $T_J = 25^\circ\text{C}$ ) ( $i_F = 2.0\text{ A}$ , $T_J = 150^\circ\text{C}$ )	$V_F$	1.45 1.20	V
Maximum Instantaneous Reverse Current (Note 1) (Rated DC Voltage, $T_J = 25^\circ\text{C}$ ) (Rated DC Voltage, $T_J = 150^\circ\text{C}$ )	$i_R$	5.0 150	$\mu\text{A}$
Maximum Reverse Recovery Time ( $i_F = 1.0\text{ A}$ , $di/dt = 50\text{ A}/\mu\text{s}$ ) ( $i_F = 0.5\text{ A}$ , $i_R = 1.0\text{ A}$ , $I_R$ to $0.25\text{ A}$ )	$t_{rr}$	75 50	ns
Maximum Forward Recovery Time ( $i_F = 1.0\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , Rec. to $1.0\text{ V}$ )	$t_{fr}$	50	ns

1. Pulse Test: Pulse Width = 300  $\mu\text{s}$ , Duty Cycle  $\leq 2.0\%$ .

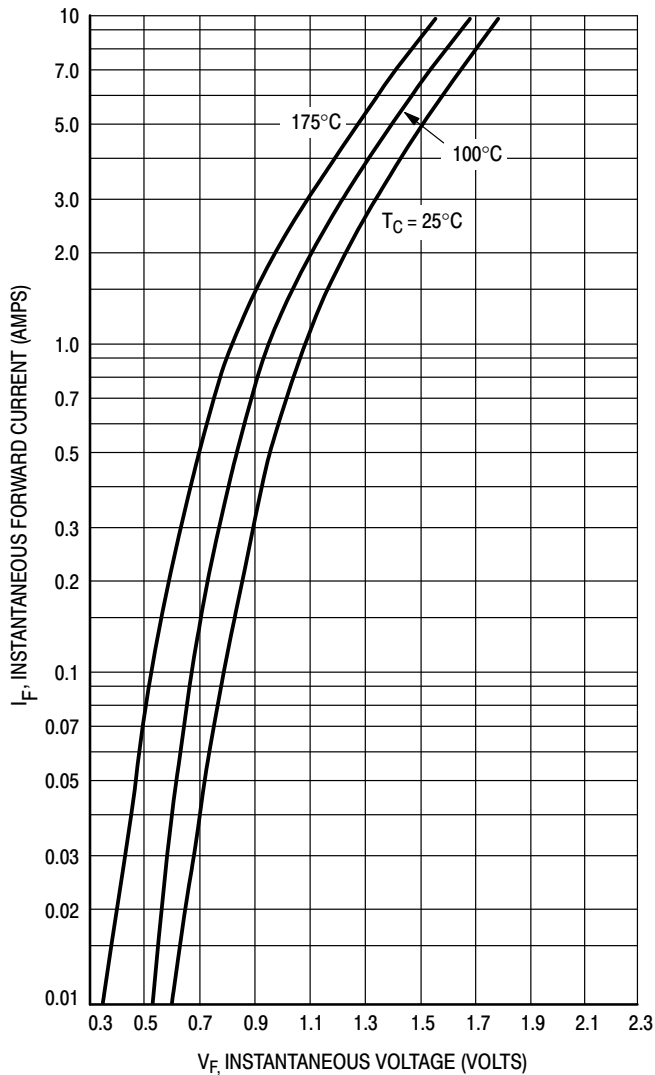


Figure 1. Typical Forward Voltage

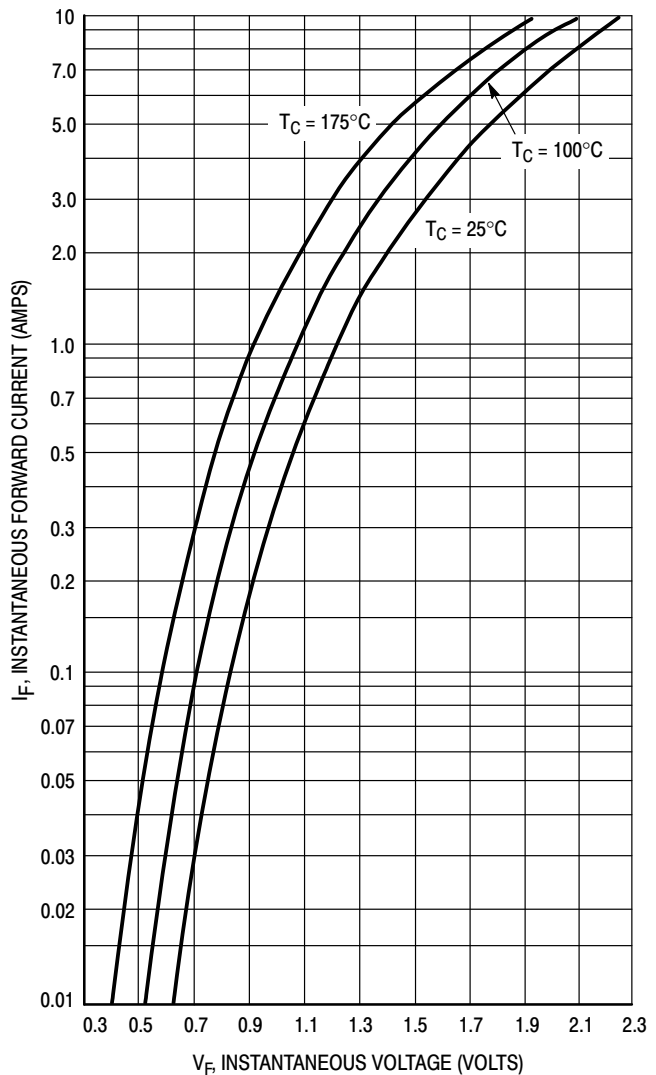
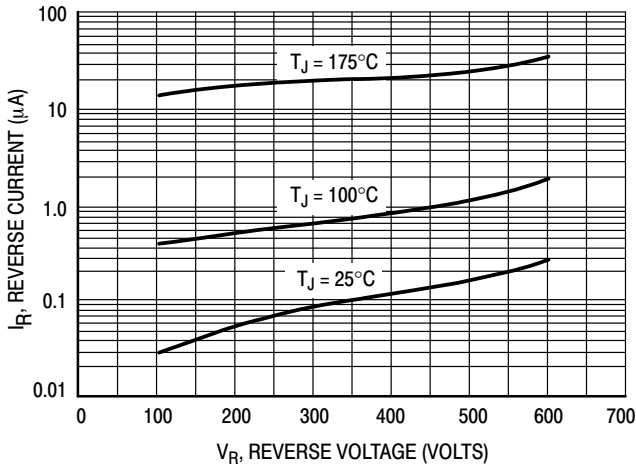


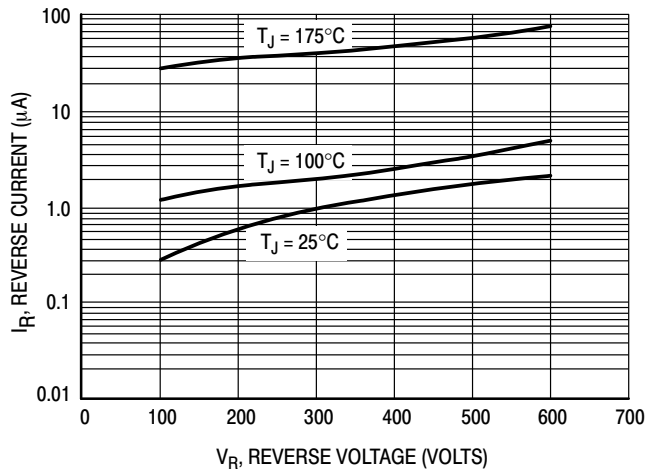
Figure 2. Maximum Forward Voltage

# MURS260T3G, SURS260T3G, SURS260T3G-VF01

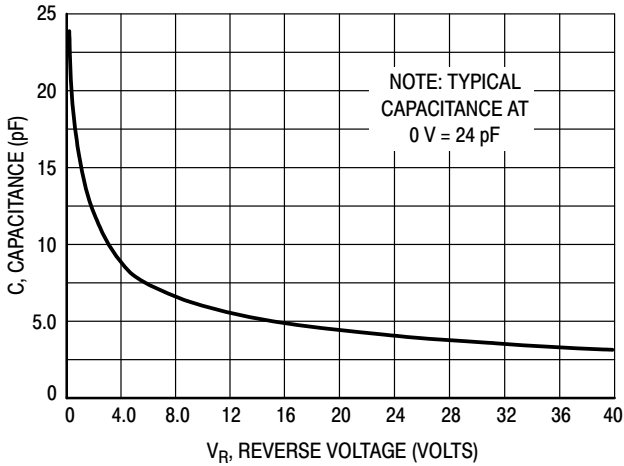


**Figure 3. Typical Reverse Current\***

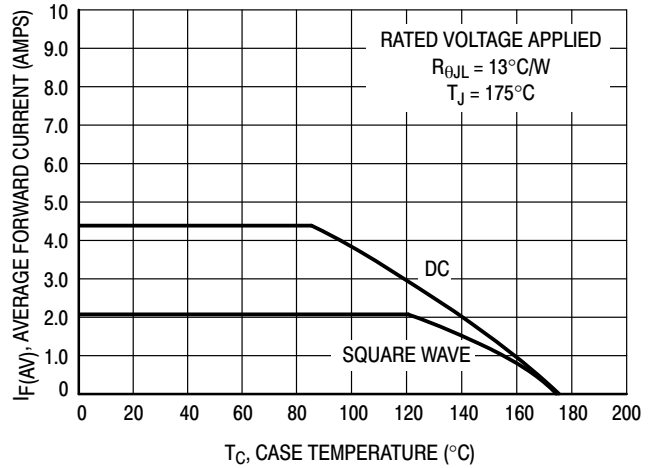
\* The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these same curves if applied  $V_R$  is sufficiently below rated  $V_R$ .



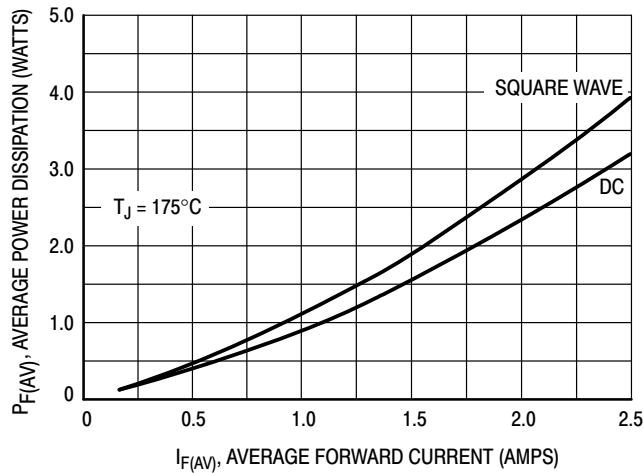
**Figure 4. Maximum Reverse Current**



**Figure 5. Typical Capacitance**



**Figure 6. Current Derating, Case**



**Figure 7. Power Dissipation**

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®



SCALE 1:1

Polarity Band

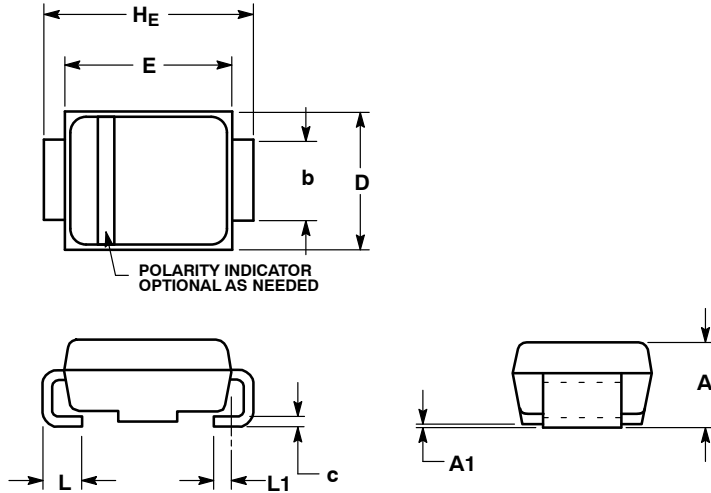


SCALE 1:1

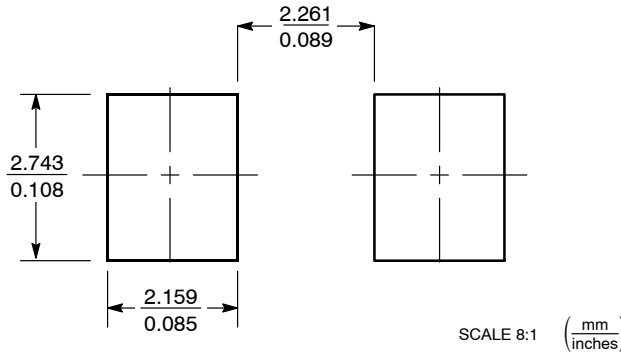
Non-Polarity Band

**SMB**  
CASE 403A-03  
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**SOLDERING FOOTPRINT\***

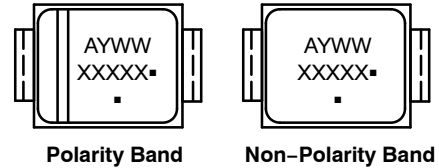


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION b SHALL BE MEASURED WITHIN DIMENSION L1.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.95	2.30	2.47	0.077	0.091	0.097
A1	0.05	0.10	0.20	0.002	0.004	0.008
b	1.96	2.03	2.20	0.077	0.080	0.087
c	0.15	0.23	0.31	0.006	0.009	0.012
D	3.30	3.56	3.95	0.130	0.140	0.156
E	4.06	4.32	4.60	0.160	0.170	0.181
HE	5.21	5.44	5.60	0.205	0.214	0.220
L	0.76	1.02	1.60	0.030	0.040	0.063
L1	0.51 REF			0.020 REF		

**GENERIC MARKING DIAGRAM\***



- XXXXX = Specific Device Code
  - A = Assembly Location
  - Y = Year
  - WW = Work Week
  - = Pb-Free Package
- (Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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